

**EXPEDITED PROCEDURE – EXAMINING GROUP 2813**

**S/N 10/670,975**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Kum Foo Leong et al.	Examiner:	Colleen E Rodgers
Serial No.:	10/670,975	Group Art Unit:	2813
Filed:	September 25, 2003	Docket No.:	884.951US1
Title:	STITCHED MICRO-VIA TO ENHANCE ADHESION AND MECHANICAL STRENGTH		
Assignee:	Intel Corporation	Customer Number:	21186

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**AMENDMENT & RESPONSE UNDER 37 C.F.R. 1.116**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In response to the Final Office Action mailed December 13, 2006, please amend the application as follows: